

### 1.6x0.8x0.5mm BI-COLOR SURFACE MOUNT **LED**



**ATTENTION** 

OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES** 

Part Number: APHB1608ZGSYKJ3C

Green Super Bright Yellow

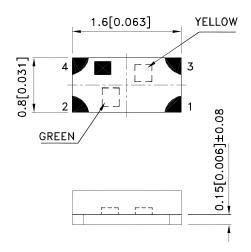
### **Features**

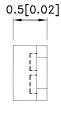
- 1.6mmX0.8mm SMT LED, 0.5mm thickness.
- · Compatible with reflow soldering.
- Available in various color combination.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability.
- RoHS compliant.

### **Descriptions**

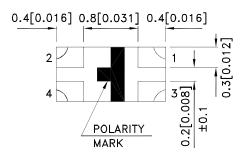
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- The Super Bright Yellow device is based on light emitting diode chip made from AlGaInP.
- Electrostatic discharge and power surge could damage
- It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

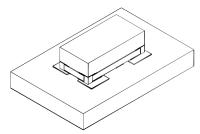
### **Package Dimensions**















- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice. 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		<i>,</i>	Min.	Тур.	201/2
APHB1608ZGSYKJ3C	Green (InGaN)	Water Clear	200	350	- 130°
	Super Bright Yellow (AlGaInP)	vvalei Ciedi	200	300	

### Notes:

- 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green Super Bright Yellow	515 590		nm	IF=20mA
λD [1]	Dominant Wavelength	Green Super Bright Yellow	525 590		nm	Ir=20mA
Δλ1/2	Spectral Line Half-width	Green Super Bright Yellow	30 20		nm	Ir=20mA
С	Capacitance	Green Super Bright Yellow	45 45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green Super Bright Yellow	3.3 2	4.1 2.5	V	IF=20mA
lR	Reverse Current	Green Super Bright Yellow		50 10	uA	V <sub>R</sub> = 5V

- Notes:

  1. Wavelength: +/-1nm.

  2. Forward Voltage: +/-0.1V.

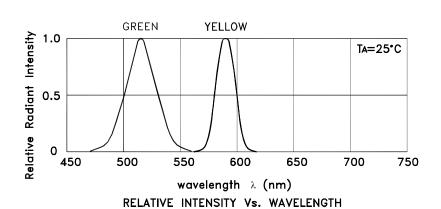
  3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

## Absolute Maximum Ratings at TA=25°C

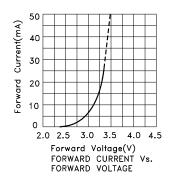
Parameter	Green	Super Bright Yellow	Units		
Power dissipation	102.5	75	mW		
DC Forward Current	25	30	mA		
Peak Forward Current [1]	150	140	mA		
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

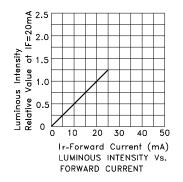
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

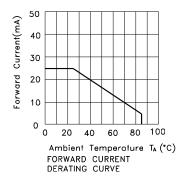
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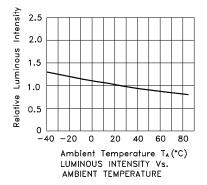


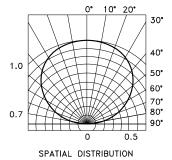
## APHB1608ZGSYKJ3C Green





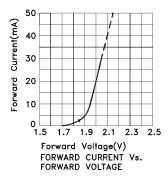


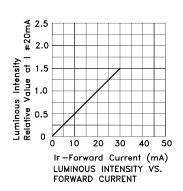


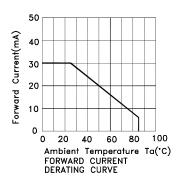


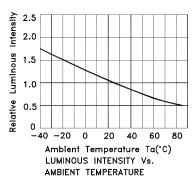
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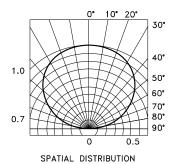
## **Super Bright Yellow**









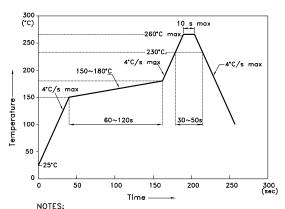


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### APHB1608ZGSYKJ3C

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

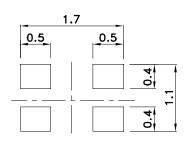
Reflow Soldering Profile For Lead-free SMT Process.



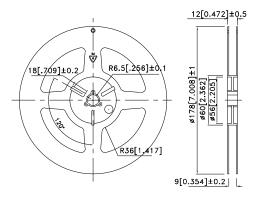
- NOTES: 1.We recommend the reflow temperature 245°C( $\pm$ /-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

  3.Number of reflow process shall be 2 times or less.

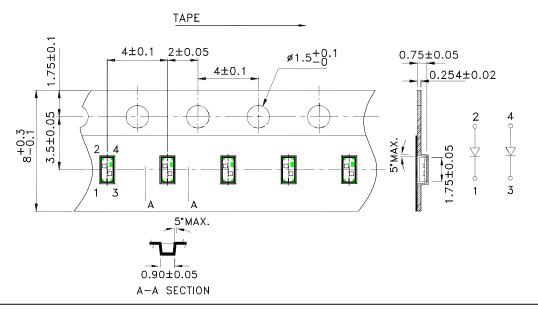
### **Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)



### **Reel Dimension**



### **Tape Dimensions** (Units: mm)



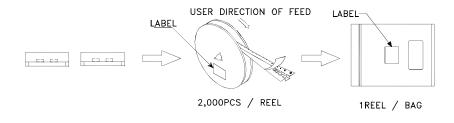
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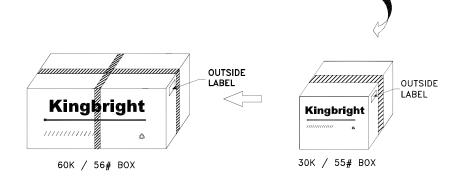
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### **PACKING & LABEL SPECIFICATIONS**

### APHB1608ZGSYKJ3C







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